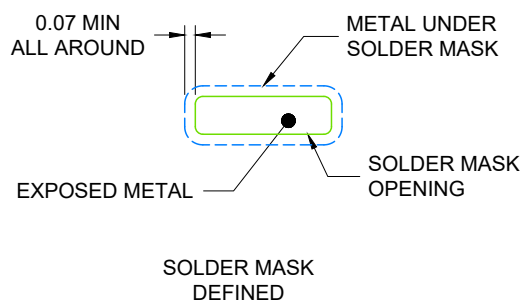
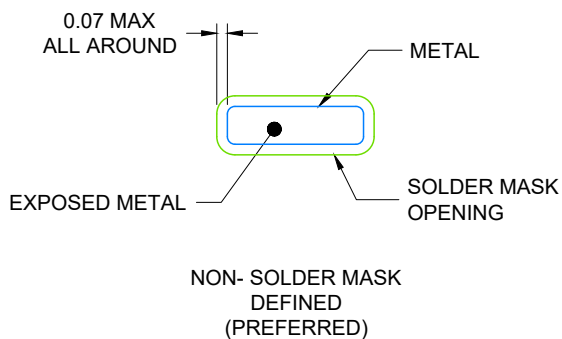
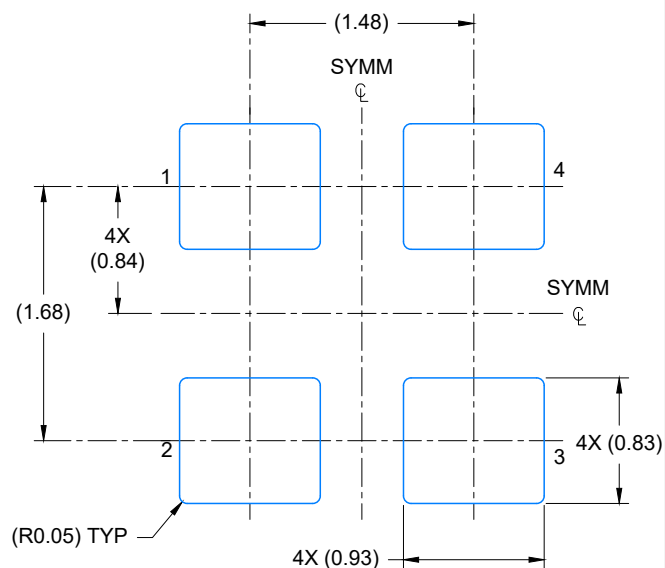
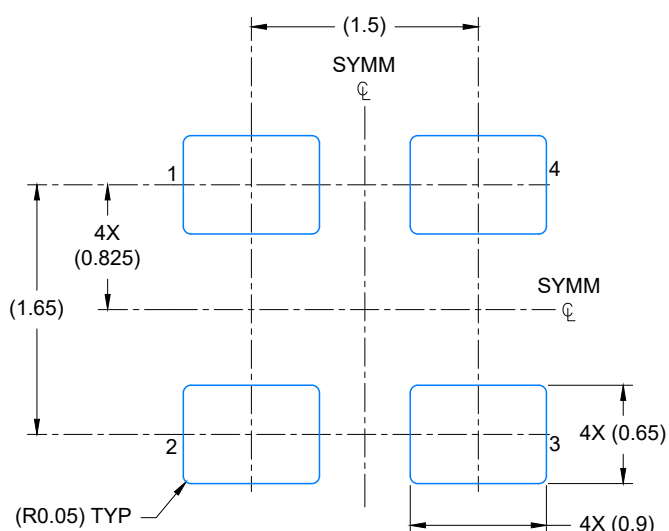


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## NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



## SOLDER MASK DETAILS

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NOTES: (continued)

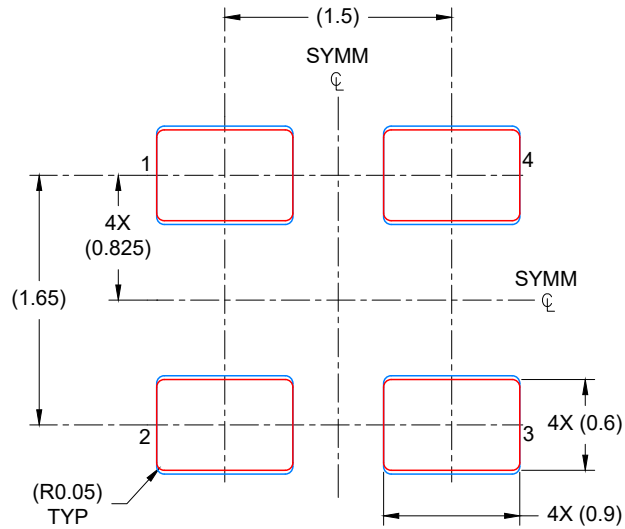
- For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)) .

# EXAMPLE STENCIL DESIGN

DLF0004B

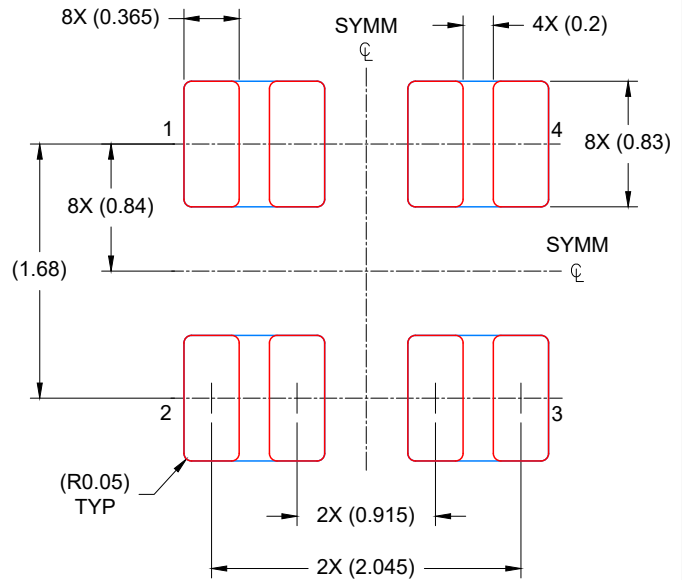
VSON - 1 mm max height

PLASTIC QUAD FLAT PACK-NO LEAD



**SOLDER PASTE EXAMPLE**  
BASED ON 0.125 mm THICK STENCIL

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
ALL PADS: 92%  
SCALE: 20X



**UNIVERSAL SOLDER PASTE EXAMPLE**  
BASED ON 0.125 mm THICK STENCIL

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
ALL PADS: 83%  
SCALE: 20X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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